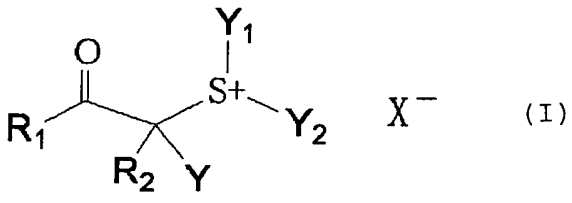
What is claimed is:

1. A photosensitive composition comprising a compound capable of generating an acid upon irradiation with an actinic ray, the compound being represented by the following general formula (I):



(I)

wherein R_1 represents an alkyl group;

R_2 represents a hydrogen atom, an alkyl group, or an aryl group;

Y represents an alkyl group;

Y_1 and Y_2 may be the same or different and each represents an alkyl group, an aryl group, an aralkyl group, or a hetero atom-containing aromatic group;

R_1 and R_2 may be bonded to each other to form a ring;

R_2 and Y may be bonded to each other to form a ring;

Y_1 and Y_2 may be bonded to each other to form a ring;

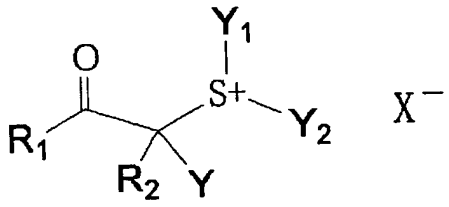
two or more structures of the general formula (I) may be bonded to each other at any position of R_1, R_2 or Y, or Y_1 or Y_2 via a connecting group; and

X^- represents a non-nucleophilic anion.

2. A positive photosensitive composition comprising:

(A) a compound capable of generating an acid upon irradiation with an actinic ray, the compound being represented by the following general formula (I); and

(B) a resin that is decomposed by the action of an acid to increase its solubility in an alkaline developer:



(I)

wherein R_1 represents an alkyl group;

R_2 represents a hydrogen atom, an alkyl group, or an aryl group;

Y represents an alkyl group;

Y_1 and Y_2 may be the same or different and each represents an alkyl group, an aryl group, an aralkyl group, or a hetero atom-containing aromatic group;

R_1 and R_2 may be bonded to each other to form a ring;

R_2 and Y may be bonded to each other to form a ring;

Y_1 and Y_2 may be bonded to each other to form a ring;

two or more structures of the general formula (I) may be bonded to each other at any position of R_1, R_2 or Y, or Y_1 or Y_2 via a connecting group; and

X^- represents a non-nucleophilic anion.

3. The positive photosensitive composition as described in claim 2, wherein the resin (B) contains a hydroxystyrene structural unit.

4. The positive photosensitive composition as described in claim 2, wherein the resin (B) contains a monocyclic or polycyclic alicyclic hydrocarbon structure.

5. The positive photosensitive composition as described in claim 4, wherein the resin (B) further contains a repeating unit having a lactone structure.

6. The positive photosensitive composition as described in claim 2, wherein the resin (B) contains a fluorine atom.

7. The positive photosensitive composition as described in claim 2, which further comprises (C) a dissolution inhibiting compound having a molecular weight of not more than 3,000, which is decomposed by the action of an acid to increase its solubility in an alkaline developer.

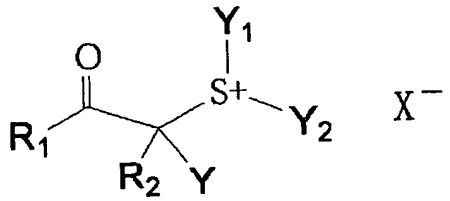
8. A positive photosensitive composition comprising:

(A) a compound capable of generating an acid upon

irradiation with an actinic ray, the compound being represented by the following general formula (I);

(D) an alkaline developer-soluble resin; and

(C) a dissolution inhibiting compound having a molecular weight of not more than 3,000, which is decomposed by the action of an acid to increase its solubility in an alkaline developer:



(I)

wherein R_1 represents an alkyl group;

R_2 represents a hydrogen atom, an alkyl group, or an aryl group;

Y represents an alkyl group;

Y_1 and Y_2 may be the same or different and each represents an alkyl group, an aryl group, an aralkyl group, or a hetero atom-containing aromatic group;

R_1 and R_2 may be bonded to each other to form a ring;

R_2 and Y may be bonded to each other to form a ring;

Y_1 and Y_2 may be bonded to each other to form a ring;

two or more structures of the general formula (I) may be bonded to each other at any position of R_1, R_2 or Y, or Y_1 or Y_2 via a connecting group; and

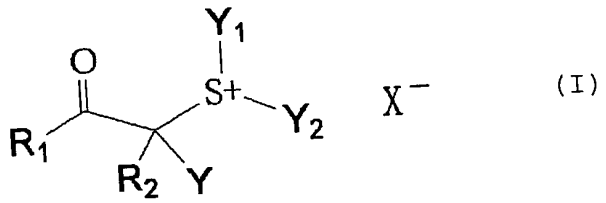
X^- represents a non-nucleophilic anion.

9. A negative photosensitive composition comprising:

(A) a compound capable of generating an acid upon irradiation with an actinic ray, the compound being represented by the following general formula (I);

(D) an alkaline developer-soluble resin; and

(E) an acid crosslinking agent capable of crosslinking with the alkaline developer-soluble resin by the action of an acid:



(I)

wherein R_1 represents an alkyl group;

R_2 represents a hydrogen atom, an alkyl group, or an aryl group;

Y represents an alkyl group;

Y_1 and Y_2 may be the same or different and each represents an alkyl group, an aryl group, an aralkyl group, or a hetero atom-containing aromatic group;

R_1 and R_2 may be bonded to each other to form a ring;

R_2 and Y may be bonded to each other to form a ring;

Y_1 and Y_2 may be bonded to each other to form a ring;

two or more structures of the general formula (I) may be bonded to each other at any position of R_1, R_2 or Y, or Y_1 or Y_2 via a connecting group; and

X^- represents a non-nucleophilic anion.

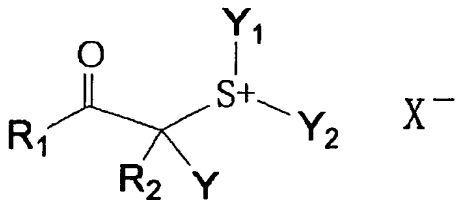
10. The photosensitive composition as described in claim 1, which further comprises (F) a basic compound.

11. The photosensitive composition as described in claim 1, which further comprises (G) a surfactant containing at least one of a fluorine atom and a silicon atom.

12. The photosensitive composition as described in claim 1, wherein each of the R_2 and Y in the formula (I) represents an alkyl group having 1 to 20 carbon atoms.

13. The photosensitive composition as described in claim 1, which further comprises at least one of an arylsulfonium compound and a compound having a phenacylsulfonium salt structure.

14. An acid generator represented by the following general formula (I):



(I)

wherein R_1 represents an alkyl group;

R_2 represents a hydrogen atom, an alkyl group, or an aryl group;

Y represents an alkyl group;

Y_1 and Y_2 may be the same or different and each represents an alkyl group, an aryl group, an aralkyl group, or a hetero atom-containing aromatic group;

R_1 and R_2 may be bonded to each other to form a ring;

R_2 and Y may be bonded to each other to form a ring;

Y_1 and Y_2 may be bonded to each other to form a ring;

two or more structures of the general formula (I) may be bonded to each other at any position of R_1, R_2 or Y, or Y_1 or Y_2 via a connecting group; and

X^- represents a non-nucleophilic anion.

15. A method of forming a resist pattern, which comprises: forming a film including the photosensitive composition described in claim 1; irradiating the film with an actinic ray; and developing the irradiated film.